RECIPIENT	

SPECIFICATIONS

SG-211SEE MODEL:

A13-173-1B SPEC. No.:

Jun. 3. 2013 **DATE:**

SEIKO EPSON CORPORATION

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SPECIFICATIONS

1. Application

This document is applicable to the crystal oscillator that are delivered to from Seiko Epson Corp.

This product is compliant with RoHS Directive.

This Product supplied (and any technical information furnished, if any) by Seiko Epson Corporation shall not be used for the development and manufacture of weapon of mass destruction or for other military purposes. Making available such products and technology to any third party who may use such products or technologies for the said purposes are also prohibited.

This product listed here is designed as components or parts for electronics equipment in general consumer use. We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an extra high reliability, such as satellite, rocket and other space systems, and medical equipment, the functional purpose of which is to keep life.

2. Model

The model is SG-211SEE

3. Packing

It is subject to the packing standard of Seiko Epson Corp.

4. Warranty

Defective parts which are originated by us are replaced free of charge in case defects are found within 12 months after delivery.

5. Amendment and abolishment

Amendment and/or abolishment of this specification are subject to the agreement between both parties.

6. Contents

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7. MSL

MSL level 1

[1] Absolute maximum ratings

Parameter	Symbol	Value	Unit	Note
Supply voltage	Vcc-GND	-0.6 to +6.0	V	
Storage temperature *	T_stg	-40 to +125	°C	Stored as bare product after unpacking.
Input voltage	Vin	-0.6 to Vcc+0.6	V	ST Terminal

^{*} Concerning the frequency change, please refer [8] Environmental and mechanical characteristics.

[2] Operating range

		Value				
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage	Vcc	1.6	1.8	2.2	V	
Supply voltage	GND	0.0	0.0	0.0	V	
Input voltage	Vin	GND	ı	Vcc	V	
Operating temperature	T_use	-20	+25	+70	°C	
Output load condition	L_CMOS	-	1	15	pF	

[•] Start up time(0 %Vcc \rightarrow 90 %Vcc) of power source should be more than 150 μ s.

[3] Frequency characteristics

Output frequency (Fo) 19.2 MHz

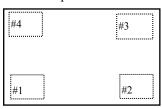
Parameter	Symbol	$Value[1 \times 10^{-6}]$	Note
Frequency tolerance *	F_tol (OSC)	D: ± 20	T_use=-20 °C to +70 °C

^{*} This includes initial frequency tolerance, temperature characteristics, input voltage characteristics(V_{CC} , \pm 10%), reflow, Aging and load characteristics, aging.

[•] By-pass capacitor (0.01 μ F to 0.1 μ F) is connected near Vcc between Vcc and GND. (Refer to [12] Recommendable patterning)

[4] Terminal assignment

Top View



Terminal name	Terminal No.	Terminal type.
ST	1	INPUT
GND	2	_
OUT	3	OUTPUT
Vcc	4	_

 \overline{ST} pin: High or open. \rightarrow Specified frequency output = enable.

 \overline{ST} pin: Low. \rightarrow Output is high impedance = disabled.

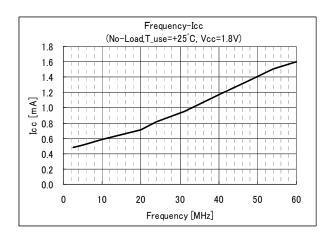
[5] Electrical characteristics

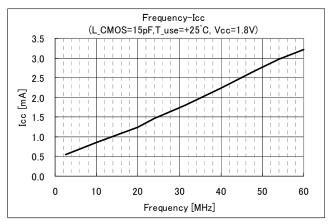
(Please see page 2 [2] Operating range)

		Value			
Parameter	Symbol	Min.	Max.	Unit	Note
Start up time	tosc	-	5	ms	t=0 at 90 %Vcc
Current consumption	Icc	-	2.3	mA	No load
Standby current	I_std	-	5.0	μΑ	ST =GND
Output rise time	tr	-	4.5	ns	$20 \% \text{ Vcc} \rightarrow 80 \% \text{ Vcc}$
Output fall time	tf	-	4.5	ns	$80 \% \text{ Vcc} \rightarrow 20 \% \text{ Vcc}$
Symmetry	SYM	45	55	%	50 % Vcc Level
High level output voltage	Voh	0.9 Vcc	-	V	IOH = -1 mA
Low level output voltage	Vol	-	0.1 Vcc	V	IOL = 1 mA
High level input voltage	Vih	0.8 Vcc	ı	V	ST terminal
Low level input voltage	VIL	-	0.2 Vcc	V	ST terminal
Input ourrant	IIH	-	10	μΑ	$V_{IN} = V_{CC}$
Input current	IIL	-10	1	μΑ	$V_{IN} = GND$
Output disable time	tstp	ı	150	ns	$\overline{\text{ST}}$ terminal High \rightarrow Low
Output enable time	tsta	-	5	ms	\overline{ST} terminal Low \rightarrow High
Input pull-up resistance	R_{UP}	50	300	kΩ	$V_{CC}=1.8V$, $\overline{ST} = 0.8V_{CC}$, at $+25^{\circ}C$
Input pun-up resistance	KUp	2	150	ΜΩ	V _{CC} =1.8V, ST =GND

Refer to [6] Test circuit [7] Timing chart

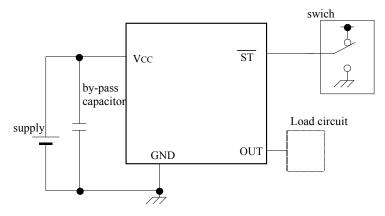
• Reference : Current consumption Typ. Value (Vcc = 1.8 V, $T_use = +25 \text{ }^{\circ}\text{C}$)





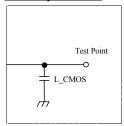
[6] Test circuit

1) Waveform observation

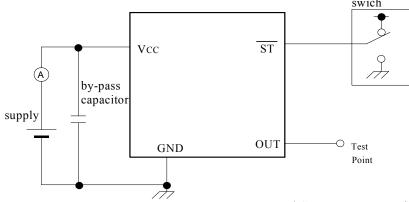


Load circuit

load capacitance



2) Current consumption



*Current consumption under the disable function should be $\overline{ST} = GND$.

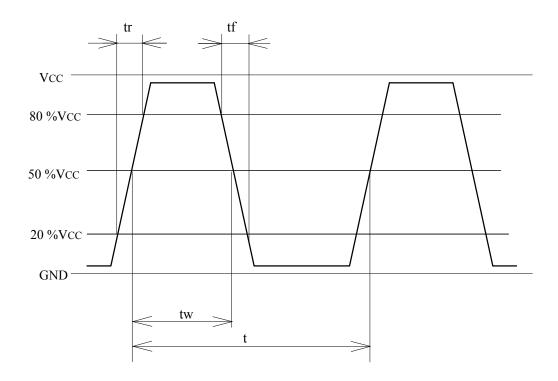
3) Condition

- (1) Oscilloscope
 - Band width should be minimum 5 times higher (wider) than measurement frequency.
 - Probe earth should be placed closely from test point and lead length should be as short as possible.
 - * Recommendable to use miniature socket. (Don't use earth lead.)
- (2) L CMOS also includes probe capacitance.
- (3) By-pass capacitor (0.01 μ F to 0.1 μ F) is placed closely between Vcc and GND.
- (4) Use the current meter whose internal impedance value is small.
- (5) Power supply
 - Start up time (0 %Vcc \rightarrow 90 %Vcc) of power source should be more than 150 µs.
 - Impedance of power supply should be as lowest as possible.

[7] Timing chart

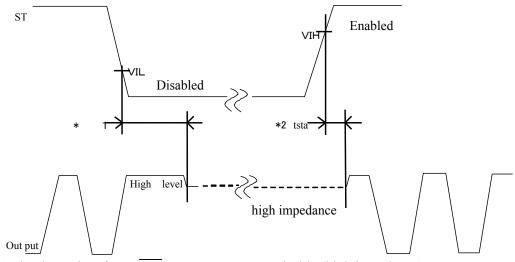
1) C-MOS load

$$SYM = tw/t \times 100 (\%)$$



2) ST function and timing

ST function	Osc. circuit	Output status		
High or Open Oscillation		Specified frequency is output : Enable		
Low	Oscillation stop	Output becomes high impedance : Disable		



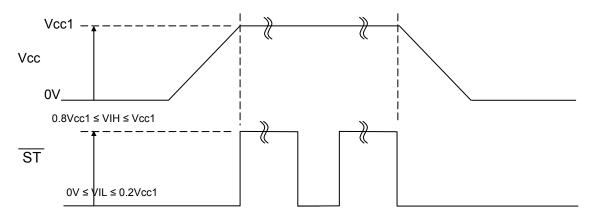
- *1 The time taken from $\overline{ST} = VIL$ to output = Disable (high impedance)
- *2 The time taken from $\overline{ST} = V_{IH}$ to output = Start

Output start : Voh \geq 90%Vcc, Vol \leq 10 %Vcc, Fout = Fo \pm 1 000×10⁻⁶

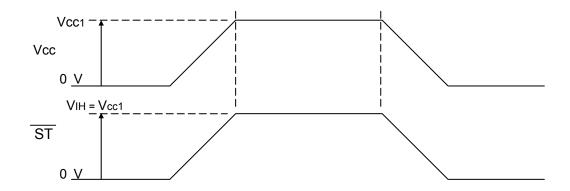
3) ST Control timing

ST function is used on the voltage below supply voltage.

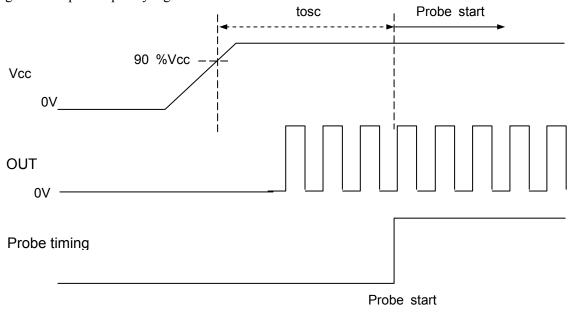
ST control timing differs from Vcc control timing



ST terminal is connected to Vcc terminal



4) Timing of an output frequency signal



[8] Environmental and mechanical characteristics

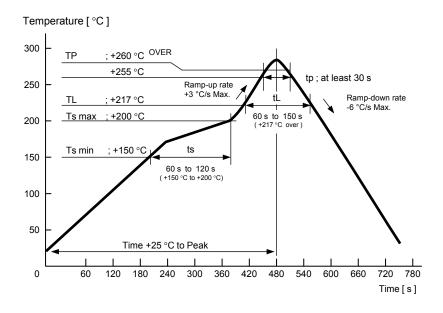
(The company evaluation condition We evaluate it by the following examination item and examination condition.)

		Value *1		Test Conditions
No.	Item	$\begin{array}{c} \Delta f / f *2 \\ [1 \times 10^{-6}] \end{array}$	Electrical characteristics	
1	High temperature storage	*3 ±10		+125 °C × 1 000 h
2	Low temperature storage	*3 ±3		-40 °C × 1 000 h
3	High temperature bias	*3 ± 5		$+85 ^{\circ}\text{C} \times \text{V}_{\text{CC}} \text{Max.} \times 1000 \text{h}$
4	Low temperature bias	*3 ±3		$-40 ^{\circ}\text{C} \times \text{V}_{\text{CC}} \text{Max.} \times 1000 \text{h}$
5	Temperature humidity bias	*3 ±5		$+85$ °C × 85 %RH × V_{CC} Max. × 1000 h
6	Temperature cycle	*3 ± 5		-40 °C ↔ +125 °C
0	Temperature cycle	.3 ±3		30 min. at each temperature 100 cycles
7	Resistance to soldering heat	± 2		Convection reflow soldering furnace (3 time) Ref. IPC/JEDEC J-STD-020D.1
8	Shock	±3	Satisfy Item [5] after test.	150 g dummy Jig (SE Standard) drop from 1 500 mm height on the Concrete 3 directions 10 times.
9	Vibration	±2		10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s ² 10 Hz \rightarrow 500 Hz \rightarrow 10 Hz 15 min./cycle 6 h (2 hours , 3 directions)
10	Seal	1×10^{-9} Pa·m ³ /s		He leakage detector
11	Solderability	Termination must be 95 % covered with fresh solder		Dip termination into solder bath at +235 °C ± 5 °C for 5 s. (Using Rosin Flux)
12	Pull - off	No peeling-off at a solder part		10 N press for 10 s \pm 1 s Ref. EIAJ ED-4702

< Notes >

- *1 Each test done independently.
- *2 Measuring 2 h to 24 h later leaving in room temperature after each test.
- *3 Initial value shall be measured after 24 h storage at room temperature after pre-conditioning. Pre-conditioning: Reflow (3 time)

Convection reflow condition (Ref. IPC/JEDEC J-STD-020D.1)



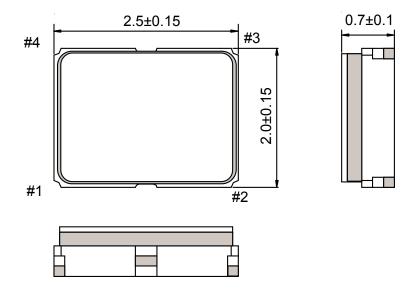
[9] Electro Static Discharge

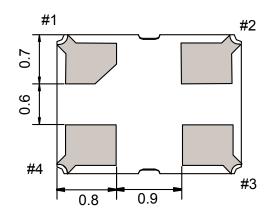
• ESD

Item	Electro Static Discharge	Test term
HBM	2 000 V Min.	EIAJ ED-4701-1 C111A,100 pF,1.5 KΩ, 3 time
MM	200 V Min.	EIAJ ED-4701-1 C111,200 pF, 0 Ω, 1 time

[10] Dimensions and marking layout

1) Dimensions

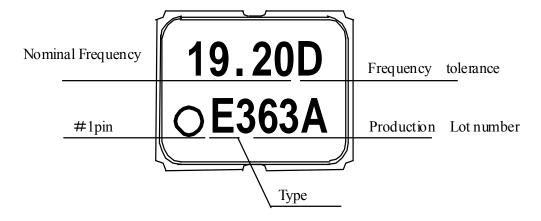




Terminal treatment: Au plating

Unit: mm

2) Marking layout



- ◆ The above marking layout shows only marking contents and their approximate position and it is not for font, size and exact position.
- ◆ Output frequency shall indicate 5 digits (include decimal point), if the value of frequency over 5 digits, the least significant digits will be omitted.

[11] Notes

- 1) This device is made with C-MOS IC.

 Please take necessary precautions to prevent damage due to electrical static discharge.
- 2) Epson Toyocom recommends a $0.01~\mu F$ to $0.1~\mu F$ capacitor must be connected near Vcc between Vcc and GND to obtain stable operation and protect against power line ripple.
- 3) Vcc and GND pattern shall be as large as possible so that high frequency impedance shall be small.
- 4) Epson Toyocom cannot recommend to put filtering element into power line so as to reduce noise. Oscillator might be unstable oscillation because high frequency impedance of power line become higher. When use filtering element, please verify electrical construction and or element's spec.
- 5) Epson Toyocom doesn't recommend to power on from intermediate electric voltage or extreme fast power on, Those powering conditions may cause no oscillation or abnormal oscillation.
- 6) Power ripple: 200 mV P-P max. Start up time (0 %Vcc→90 %Vcc) of power source should be more than 150 µs.
- 7) A long output line may cause irregular output, so try to make the output line as short as possible.
- 8) Other high-level signal lines may cause incorrect operation, so please do not place high level signal line close to this device.
- 9) This device contains a crystal resonator, so please don't expose excessive shock or vibration. Epson Toyocom recommends store device under normal temperature and humidity to keep the specification.
- 10) An automatic insertion is available, however, the internal crystal resonator might be damaged in case that too much shock or vibration is applied by machine condition.

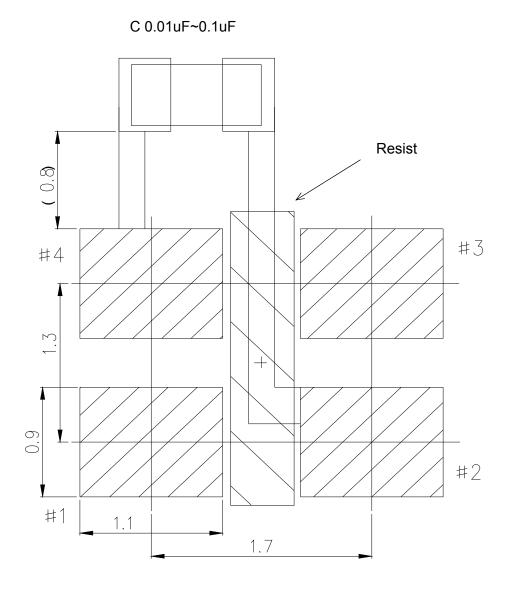
 Be sure to check your machine condition in advance.
- 11) Ultrasonic cleaning can be used on the SG-211SEE, however, since the oscillator might be damaged under some conditions, please exercise in advance.
- 12) Epson Toyocom recommends to use and store under room temperature and normal humidity to secure frequency accuracy and prevent moisture.
- 13) ST -pin has pull-up resistor internally. The resistor value is switched depending on input voltage.

 Please refer to electrical characteristics. And if ST -pin is not controlled please connect it to Vcc-pin.
- 14) Lid is electrically connected to GND. Please don't apply electrical voltage.

[12] Recommendable patterning

The soldering pad sample indicated as like following:

Soldering position (Unit: mm)



TAPING SPECIFICATION

I. Application

This standard will apply to 2.5×2.0 Ceramic package.

Spec: CG package

II. Contents

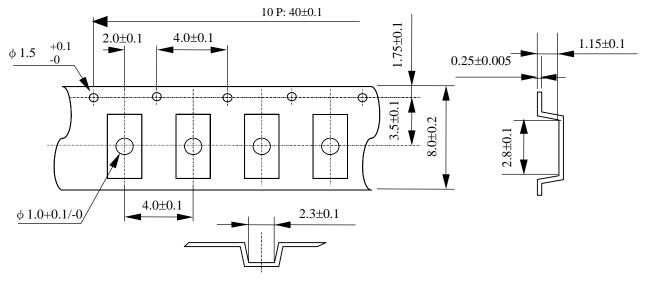
Item No.	Item	Page
[1]	Taping specification	1 to 2
[2]	Inner carton	3
[3]	Shipping carton	
[4]	Marking	4
[5]	Quantity	
[6]	Storage environment	
[7]	Handling	

[1] Taping specification

Subject to 「EIA-481」 and 「IEC-60286」

(1) Tape dimensions

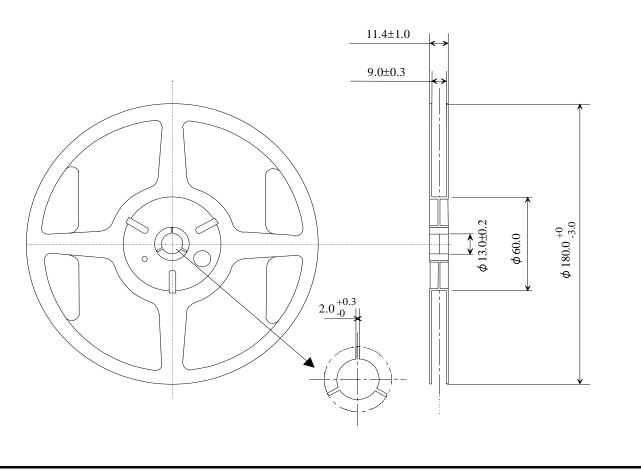
Material of the carrier tape : PSMaterial of the top tape : PET+PE

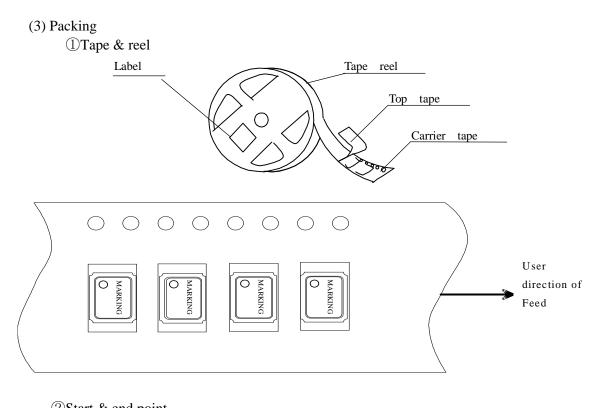


Unit: mm

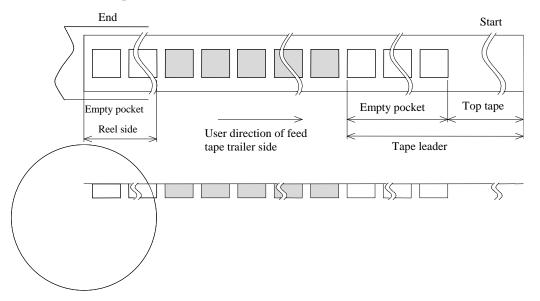
(2) Reel dimensions

Material of the reel: Conductive polystyrene





②Start & end point



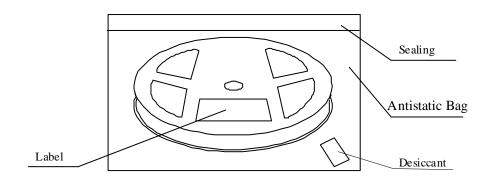
Ite	Empty space	
Tape leader	Top tape	Min. 1 000 mm
	Carrier tape Min. 160 mm	
Tape trailer	Top tape	Min. 0 mm
	Carrier tape	Min. 160 mm

(4) Peel force of the cover tape

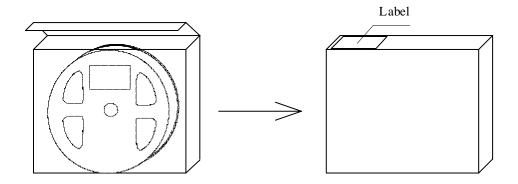
- \bigcirc angle : cover tape during peel off and the direction of unreeling shall be 165° to 180°.
- ② peel speed: 300 mm / min.

[2] Inner carton

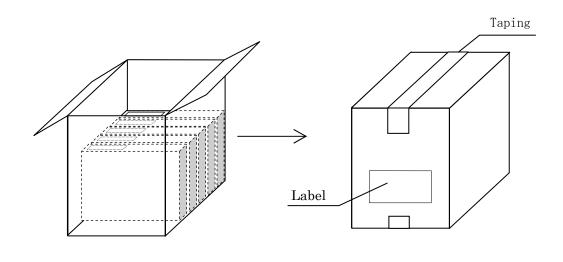
a) Packing to antistatic bag



b) Packing to inner carton



(3) Shipping carton



[4] Marking

- (1) Reel marking
 - Reel marking shall consist of:
 - 1) Parts name
 - 2) Quantity
 - 3) Manufacturing date or symbol
 - 4) Manufacturer's date or symbol
 - 5) Others (if necessary)
- (2) Inner carton marking
 - · Same as reel marking.
- (3) Shipping carton marking
 - Shipping carton marking shall consist of :
 - 1) Parts name
 - 2) Quantity
- [5] Quantity
 - · 3 000 pcs./reel
- [6] Storage environment
 - (1) Before open the packing, we recommend to keep less than +30 °C and 85 %RH of Humidity, and to use it less than 6 months after delivery.
 - (2) We recommend to open Package in immediately before use. After open Package, We recommend to keeps less than 6 month. No need dry air before soldering work if it is less than temperature +30 °C, 85 humidity %RH.
 - (3) Not to expose the sun.
 - (4) Not to storage with some erosive chemicals.
 - (5) Nothing is allowed to put on the reel or carton to prevent mechanical damage.
- [7] Handling

• To handle with care to prevent the damage of tape, reel and products.

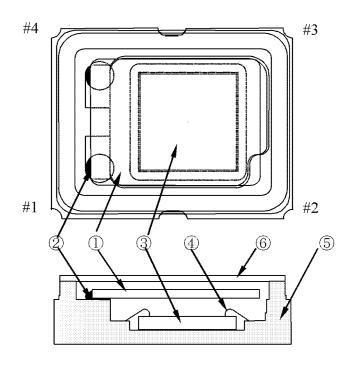
No. SG211S*E - 00 - ASE - 2

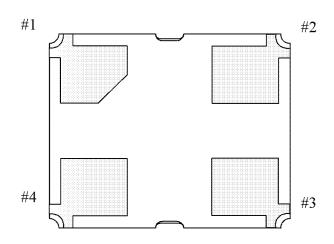
CRYSTAL OSCILLATOR: SG-211S*E

Inspection, Inspection No. Manufacturing process chart Section In Charge Standards Instruments Record Control Item Methods Appearance Dimension Microscope Sampling Data sheet Purchasing Specification 1 Inspection Section Incoming Inspection Standard ·In-coming Inspection Sampling Appearance Microscope Data sheet China Plant Manufacturing Instruction 2 Peeling Strength Scratch (Production Section) Frequency CI Meter 3 Base China Plant Manufacturing Instruction Appearance Microscope Sampling Data sheet 3 (Production Section) Sheet Sputter China Plant Manufacturing Instruction Microscope 2) Parts Mounting (IC) Appearance Sampling Data sheet 4 (Production Section) Sheet China Plant Manufacturing Instruction Bonding strength Gauge Sampling Data sheet Wire Bonding (Production Section) Appearance Microscope China Plant Manufacturing Instruction Appearance Microscope Sampling Data sheet 6 (Production Section) Sheet Crystal-Mounting China Plant Manufacturing Instruction Microscope Sampling Data sheet Appearance (Production Section) Sheet Annealing China Plant Manufacturing Instruction 8 (Production Section) Sheet Frequency Adjusting Data sheet China Plant Manufacturing Instruction Appearance Microscope Sampling (Production Section) Sheet Temporary Hermetic Sealing Appearance Microscope Sampling Data sheet China Plant Manufacturing Instruction Frequency Counter Sampling (Production Section) Sheet (10) Hermetic Sealing China Plant Manufacturing Instruction 11 (Production Section) Sheet (11) High Temp Treatment Data sheet China Plant Manufacturing Instruction Leakage Inspection Measuring equipment 100% Inspection 12 (Production Section) Sheet Visual Inspection Data sheet Appearance Sampling China Plant Manufacturing Instruction <12> Leakage 13 (Production Section) Sheet Characteristic Inspection Measuring equipment 100% Inspection Data sheet Manufacturing Instruction China Plant [13] Marking 14 (Production Section) Sheet Electrical Characteristic Measuring equipment 100% Inspection Data sheet LDL Inspection China Plant Manufacturing Instruction 15 One/Day (Production Section) Sheet Adjusting, Temp Characteristic Measuring equipment Data sheet 100% Inspection China Plant Manufacturing Instruction Inspection Electrical Characterist (Production Section) Sheet China Plant Manufacturing Instruction Appearance Microscope Sampling Data sheet (16) Temp Characteristic 17 (Production Section) Sheet Electrical Characteristic Measuring equipment Sampling Data sheet China Plant Delivery Specifications Visual Inspection 18 Visual Inspection One/Day Appearance (Inspection Section) Outgoing Inspection Standard Tape peeling Strength Peeling strength Sampling Data sheet Manufacturing Instruction Chaina Plant 19 Outgoing Inspection Quantity test machine One/Day (Production Section) Sheet Chaina Plant Manufacturing Instruction Customers Delivery 19 Taping 20 (Production Control Sheet Slip Daily Shipping List Section) Quantity Packing

10. 02. 02

Structure diagram SG-211S*E





LIST						
Name of part		Material				
1	Crystal chip	AT cut				
2	Crystal adhesive	Ag paste				
3	IC	C-MOS				
	IC conductive adhesive	Ag paste				
4	Bonding wire	Au				
(5)	Package	Ceramic (Al ₂ 0 ₂)				
6	Сар	Kovar				

RELIABILITY TEST DATA

Product Name: SG-211S*E series

The Company evaluation condition

We evaluate environmental and mechanical characteristics by the following test condition . No. G-0815A-01-001E

		TEST CONDITIONS	VALUE *1 TEST FAIL			
No.			$\Delta f/f *2$	Electrical	Qty	Qty
			$[1 \times 10^{-6}]$	characteristics	[n]	[n]
1	High temperature storage	+125 °C × 1 000 h	± 10		22	0
2	Low temperature storage	-40 °C × 1 000 h	*3 ± 3	Satisfy specification after test	22	0
3	High temperature bias	+85 °C × Spec bias × 1 000 h	*3 ± 5		22	0
4	Low temperature bias	-40 °C × Spec bias × 1 000 h	*3 ± 3		22	0
5	Temperature humidity bias	+85 °C × 85 %RH × Spec bias × 1 000 h	*3 ± 5		22	0
6	Temperature cycle	-40 °C ⇔ +125 °C 30 min at each temp. 100 cycles	*3 ± 5		22	0
7	Resistance to soldering heat	For convention reflow soldering furnace (3 times) Ref. IPC/JEDEC J-STD-020D.1	± 2		22	0
8	Shock	150 g dummy (Epson Toyocom Standard) drop from 1 500 mm height on to the concrete 3 directions 10 times	± 3		22	0
9	Vibration	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s ² $10 \text{ Hz} \rightarrow 500 \text{ Hz} \rightarrow 10 \text{ Hz}$ 15 min / cycle 6 h (2 h × 3 directions)	± 2		22	0
10	Seal	He leakage detector	1 × 10 ⁻⁹ Pa·m³/s Max.		11	0
11	Pull-off	10N press for 10s ± 1s Ref.EIAJ ED-4702	No Peeling-off at a solder part		11	0
12	Solderability	Dip termination into solder bath at $+235 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$ for $5 ^{\circ}\text{S}$ (Using Rosin Flux)	Termination must be 95 % covered with fresh solder		11	0

Notes

- 1. *1 Each test done independently.
- 2. *2 Measuring 2 h to 24 h later leaving in room temperature after each test.
- 3. *3 Initial value shall be measured after 24 h storage at room temperature after pre-conditioning. Pre-conditioning: Re-

Product Name: SG-211S*E series

